



Elemelt Technical Data Sheet **TC-955-0R02-B**

Elemelt TC-955-0R02-B is a high molecular weight copolyester resin designed for low pressure molding. This resin has the characteristics of a short open time with a high melting point. Application temperature is 180-210°C which is ideal for PCB encapsulation and durability. Adhesion can be improved with plasma treating or by coating chemical primer. This product is available in black.

1. TYPICAL SPECIFICATIONS

Appearance	: Black pellet solid.
Melting Point(°C)	: 160 ~ 170
Viscosity(dPa · s/220°C)	: 400 ~ 500
Acid Value (mg-KOH/gm)	: 3 Max.
Specific Gravity	: 1.05

2. SHORE-A HARDNESS

Measured Temperature °C	Shore-A Hardness
23	67
40	65
60	58
80	55
100	43
120	20

4. PEEL STRENGTH

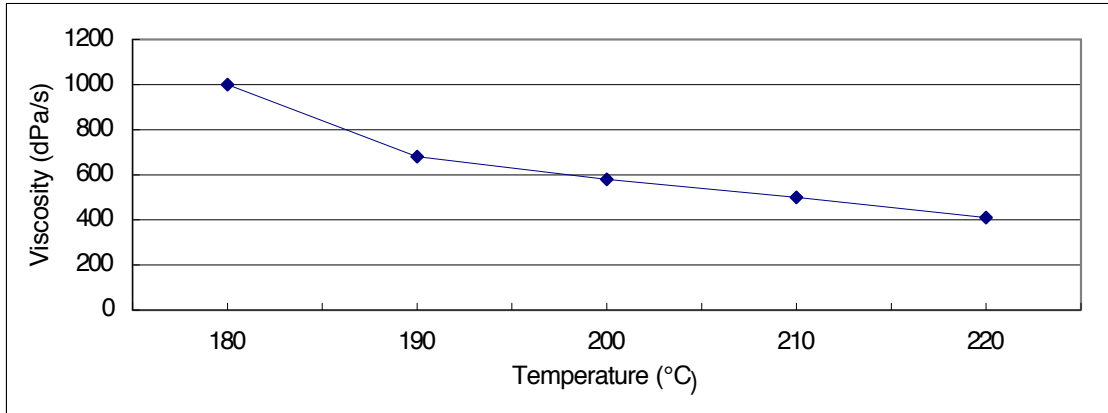
Maximum Peel Strength	:55 N/25mm
Average Peel Strength	: 47 N/25mm

Remarks: Test Specimen : glass epoxy
Tensile Speed : 50mm/min, At RH23°C 50%

4. WATER ABSORPTION

Water Absorption(%) : 0.4(RH23°C 50%,1Day)

5. VISCOSITY CURVE VERSUS TEMPERATURE



6. APPLICATION TEMPERATURE

180°C ~210°C

7. PACKAGING

20 kg net, paper bag.

8. STORAGE CONDITIONS

Store in sealable container once shipping bag has been opened. Copolyesters are sensitive to high humidity and will absorb atmospheric moisture. Be sure to dry polyester resin at 60°C for more than 4 hours before use. Shelf life is 6 months with proper storage and at a temperature below 30°C.

Note:

Our data and recommendations in this sheet do not constitute a warranty or representation for which we assume legal responsibility. They are offered only for your reference, investigation and verification, not guaranteed values.

Before using this product, please check or study carefully, that this grade is suitable for your purpose, application and process condition, etc.